

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A piezoelectric device having a structure in which a piezoelectric resonator element is bonded to electrodes provided on a package base, comprising:

silicone-based conductive adhesives;

mounting electrodes provided on the package base, to which a driving voltage is carried via conduction paths, and on which the piezoelectric resonator element is mounted, the mounting electrodes defining surfaces; and

conductive anchor members which are disposed on the surfaces of the mounting electrodes and which are formed of a material having high adhesion to the surfaces of the mounting electrodes, the piezoelectric resonator element being bonded to the conductive anchor members with the silicone-based conductive adhesives provided therebetween,

wherein the conductive anchor members include a conductive adhesive formed of a rigid resin.

2. (Canceled)

3. (Currently Amended) The piezoelectric device according to ~~Claim 2~~ Claim 1, the conductive anchor members including at least one of an epoxy-based and a polyimide-based conductive adhesive.

4. (Withdrawn-Currently Amended) A method for manufacturing a piezoelectric device, comprising:

bonding a piezoelectric resonator element to electrodes provided on a package base, the bonding step including:

adhering a conductive adhesive to a tip of a jig, the conductive adhesive being in a molten state;

moving a jig in a direction substantially perpendicular to a surface of a mounting electrode, which is provided on the package base and to which a voltage is carried via a conduction path, so that the jig is brought into contact with the surface of the mounting electrode, the conductive adhesive adhered to the tip of the jig having superior adhesion to a material of the surface of the mounting electrode;

subsequently separating the jig from the mounting electrode in a direction perpendicular to the mounting electrode so as to form an anchor member on the surface of the mounting electrode; and

placing the piezoelectric resonator element on the anchor member provided with a silicone-based conductive adhesive thereon so as to be bonded to the anchor member,

wherein the adhering step includes adhering conductive adhesive to the jig that is a conductive adhesive including a rigid resin.

5. (Canceled)

6. (Withdrawn-Currently Amended) The method for manufacturing a piezoelectric device according to ~~Claim 5~~ Claim 4, the adhering step including adhering conductive adhesive to the jig that is at least one of an epoxy-based and a polyimide-based conductive adhesive.

7. (Withdrawn) The method for manufacturing a piezoelectric device according to Claim 4, the moving step including moving a jig that is a stamping jig.

8. (New) The piezoelectric device according to Claim 1, wherein the surface of the mounting electrode is a gold (Au) electrode film.

9. (New) The method for manufacturing a piezoelectric device according to Claim 4, wherein the surface of the mounting electrode is a gold (Au) electrode film.